

ABSTRACT

A method of manufacturing a chip PTC thermister comprises a piece of conductive polymer having a PTC characteristic and metal foils formed by patterning and provided on the upper and the lower sides of the piece under pressure integrally into a sheet, making a hole part in the sheet, applying a protective coat serving as plating resist to upper and lower sides of the sheet , forming an electrode on the by electroplating, and cutting the sheet into a chip. The protective coat is made of a material applicable at a temperature equal to or lower than the melting point of the conductive polymer. The processing temperatures at the step from the step of making a hole part in the sheet to the pre-processing step of the step of forming an electrode by electroplating on the sheet are not above the melting point of the conductive polymer.